

# Supply Chain Explorer

By the Emerging Technology Observatory

This is an export from the ETO Supply Chain Explorer, available at: <https://chipexplorer.eto.tech> You can see the web version of this content at <https://chipexplorer.eto.tech/?filter-choose=input-resource&input-resource=N57>.

## Chemical mechanical planarization

After etching and cleaning, the wafer surface is flattened in a process called chemical mechanical planarization (CMP) to allow a new layer of features to be added. CMP tools are critical for chip fabrication, but not as complex as other tools, such as lithography and deposition tools.